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RESIN SEALED SEMICONDUCTOR DEVICE

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Abstract:

PURPOSE: To provide a resin sealed semiconductor device which can cope with the increased number of terminals and the positional deviations and flatness problems of outer leads.

CONSTITUTION: Each inner lead of a resin sealed semiconductor device has a lead frame material united with the inner lead in one body and a columnar terminal pillar 133 which has the same thickness as the lead frame material has and is used for connecting the inner lead to an external circuit and the terminal pillar 133 is provided in the direction perpendicular to the thickness direction of the inner lead on the outside of the inner lead and has a terminal section composed of solder, etc., on its front end face. The terminal section and the external side face of the terminal pillar are exposed from the sealing resin section. The inner lead formed in a square cross section has a first surface 131Aa, a second surface 131Ab, a third surface 131Ac, and a fourth surface 131Ad and the first surface 131Aa is formed in the same plane with one surface of the other part having the same thickness as the lead frame material has and is counterposed to the second surface 131Ab. The third and fourth surfaces 131Ac and 131Ad are recessed toward the inside of the inner lead.

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